

Title (en)

CHIP PACKAGE WITH MOLDED UNDERFILL

Title (de)

CHIP-GEHÄUSE MIT SPRITZGEGOSSENER UNTERFÜLLUNG

Title (fr)

BOITIER DE MICROCIRCUIT A COMPLEMENT MOULE

Publication

EP 1190448 A1 20020327 (EN)

Application

EP 99923109 A 19990514

Priority

US 9910771 W 19990514

IPC 1-7

H01L 23/28; H01L 23/48; H01L 23/29; H01L 21/56; H01L 23/31

IPC 8 full level

H01L 21/56 (2006.01); **H01L 21/60** (2006.01); **H01L 23/28** (2006.01); **H01L 23/29** (2006.01); **H01L 23/31** (2006.01); **H01L 23/48** (2006.01)

CPC (source: EP KR)

H01L 23/16 (2013.01 - KR); **H01L 2224/32225** (2013.01 - EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/15151** (2013.01 - EP); **H01L 2924/15311** (2013.01 - EP)

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

EP 1190448 A1 20020327; EP 1190448 A4 20041124; JP 2003500833 A 20030107; KR 20020035477 A 20020511

DOCDB simple family (application)

EP 99923109 A 19990514; JP 2000619029 A 19990514; KR 20017014402 A 20011112